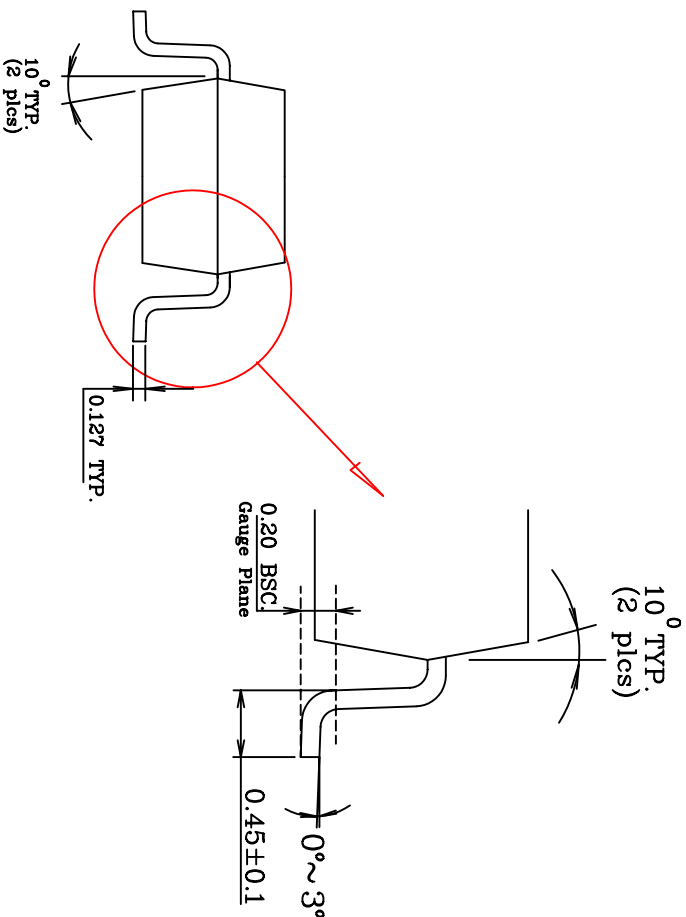
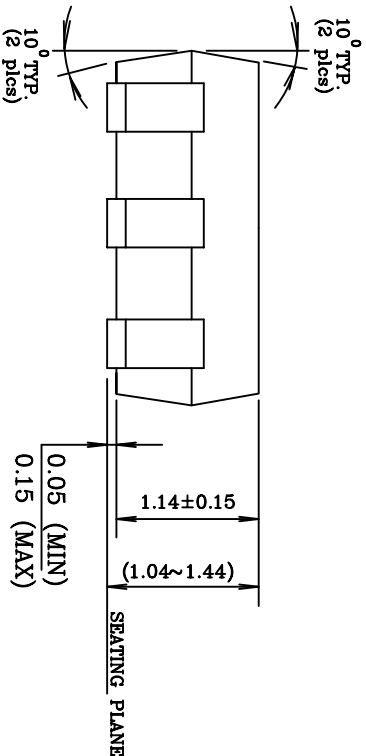
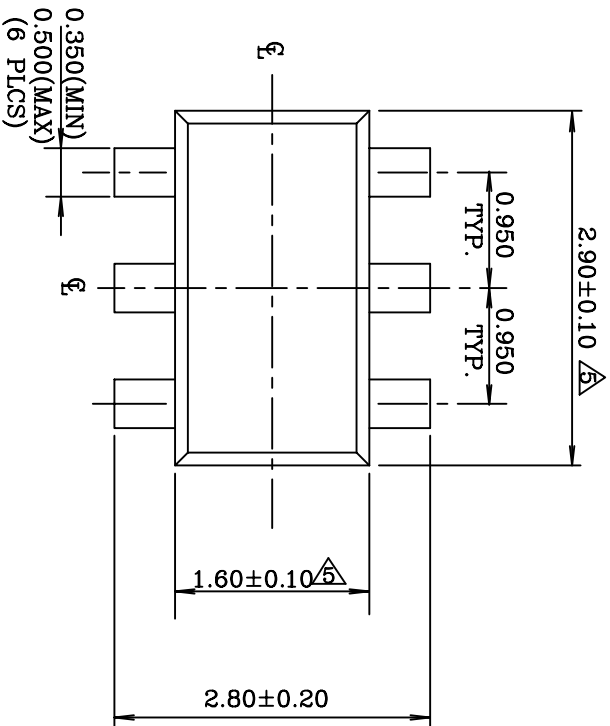




- NOTE:
1. Dimensions and tolerances are as per ANSI Y14.5M, 1982.
 2. Package surface to be mirror finish.
 3. Die is facing up for mold. Die is facing down for trim/form, ie. reverse trim/form.
 4. The footlength measuring is based on the gauge plane method.
- $\triangle 5$ Dimensions are exclusive of mold flash and gate burr.

COPPER FRAME

D	Note: Metal burr revise to gate burr as per Jedec Spec. Lead width change to 0.35-0.50 (was 0.36-0.52) as per Jedec spec.	18/01/02	ANDREW	PT
C	Add note no.5.	15/01/01	ANDREW	PT
A	Change lead width to 0.360(Min)&0.520(Max) - (was 0.4)	03/06/99	ANDREW	PT
A	L/F Thickness changed to 5 mils. (Was 4 mils)	19/08/96	CH TAN	MGT.
0	Original Design.	08/05/96	CH TAN	CH TAN
REV.	DESCRIPTION	DATE	BY	APPD

TOLERANCES		UNIT:	SCALE:
REFER TO THE SPECIFICATION ABOVE.		MM	NTS
		SYMBOL	
DWN:	ANDREW	DATE:	18/01/02
APPD:	CH TAN	DATE:	
APPD:	CK TANG	DATE:	
APPD:	CW CHAI	DATE:	
APPD:	SRI	DATE:	
DWG. NO:	SOT-P-C06	REV.:	D
SOT-23 (6 LDS)			
PACKAGE CASE OUTLINE			
SHEET NO : 1 OF 1.			